# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

HP EliteDesk 705 G2 MT Business PC

---

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances: 0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td></td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove access panel
2. Remove all add-on cards
3. Remove all cables from main board and devices
4. Remove system fan
5. Remove front bezel and hood lock
6. Remove SD card reader and ODD
7. Remove all equipped HDD
8. Remove PSU
9. Remove M/B
10. Remove heat sink from M/B
11. Remove DDR and battery from M/B

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. Remove access panel

1. Lift the latch to release access panel of MT chassis as photo1 shown
2. Remove all add-on cards

1. Remove all of the add-on cards if sku obtained
   (See Photo2,3,4,5)
3. Remove all cables from main board and devices

1) Release all the cables have been connected between M/B and devices (See Photo6)

1) Power cable (6 pin)
2) Heat sink cable
3) 12v PWR cable (4pin)
4) Audio cable
5) Front USBx2 & card reader
6) HDD SATA & PWR
7) ODD SATA & PWR
8) System fan
9) Add on card cable
10) Hood lock cable
4. Remove system fan

1. Release system fan screws
   (See Photo7)
5. Remove front bezel and hood lock

1. Lift up 3 latches then remove front bezel
   (See Photo8,9)

2. Release tamper proof screws then release the cable from M/B
   (6-32 x .187" Security Head)
   (See Photo10,11,12)
### 6. Remove SD card reader and ODD

<table>
<thead>
<tr>
<th>Step</th>
<th>Description</th>
</tr>
</thead>
</table>
| 1    | Release 1 screw from card reader (6-32 x 0.187")  
(See Photo13) |
| 2    | Remove card reader module from chassis  
(See Photo14,15) |
| 3    | Release the latch from ODD cage then pull ODD out of cage; direction as photo16 shown  
(See Photo16,17)  
Remove the plastic latch from ODD as photo17 shown  
(See Photo18) |
7. Remove all equipped HDD

1. Lift HDD latch then pull HDD to the up right for escaping from cage  
   (See Photo19)

2. Remove HDD towards up right direction as 1st, 2nd HDD releasing  
   (See Photo20,21)
8. Remove PSU

1. Release 4 screws of PSU
   *(See Photo22)*

2. Draw PSU to the direction shown
   *(See Photo23)*
3. Release 2 screws from PSU
   (See Photo24)
4. Release 2 screws from the other side
   (See Photo25)
<table>
<thead>
<tr>
<th>Step</th>
<th>Instruction</th>
<th>Photo</th>
</tr>
</thead>
<tbody>
<tr>
<td>5</td>
<td>Cut the cable tie</td>
<td>Photo26</td>
</tr>
<tr>
<td></td>
<td>(See Photo26)</td>
<td></td>
</tr>
<tr>
<td>6</td>
<td>Slide PSU cover alone the way</td>
<td>Photo27</td>
</tr>
<tr>
<td></td>
<td>(See Photo27)</td>
<td></td>
</tr>
</tbody>
</table>
7 Remove L/N from PCB
   (See Photo28)

8 Remove fan wire from PCB
   (See Photo29)
9 Release 4 screws of PCA  
(See Photo30)

10 Remove the capacitor  
(See Photo31)
9. Remove M/B

1. Release 8 screws by order 8 to 1 to free M/B from chassis (6-32 x 0.250”)
   (See Photo32)

2. Follow the direction to drag M/B out of chassis
   (See Photo33)
## 10. Remove heat sink from M/B

<table>
<thead>
<tr>
<th></th>
<th>Photo34</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td><img src="image" alt="Heat Sink" /></td>
</tr>
</tbody>
</table>

1. Release 4 screws by order 4 to 1 to free heat sink from chassis

*(See Photo34)*
11. Remove DDR and battery from M/B

1. Release DDR by flipping latches outwards as direction shown
   *(See Photo35)*

2. Remove battery from M/B by loosening the clip outwards as direction shown
   *(See Photo36)*

Remove coin battery from MB